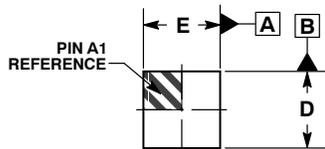




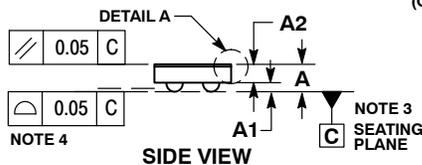
SCALE 4:1

WLCSP4, 0.84x0.84
CASE 567PC
ISSUE A

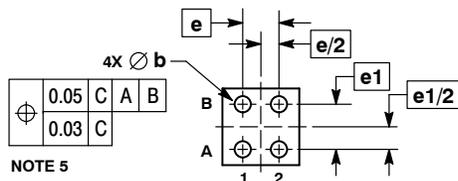
DATE 30 MAY 2017



TOP VIEW

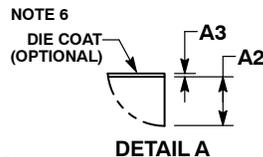
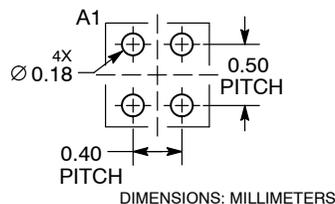


SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DETAIL A

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

| MILLIMETERS | | | |
|-------------|-----------|------|------|
| DIM | MIN | NOM | MAX |
| A | --- | --- | 0.30 |
| A1 | 0.08 | 0.10 | 0.12 |
| A2 | 0.15 REF | | |
| A3 | 0.025 REF | | |
| b | 0.16 | 0.18 | 0.20 |
| D | 0.81 | 0.84 | 0.87 |
| E | 0.81 | 0.84 | 0.87 |
| e | 0.40 BSC | | |
| e1 | 0.50 BSC | | |

GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- Y = Year
- W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|--------------------------|--|
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| DESCRIPTION: | WLCSP4, 0.84X0.84 | PAGE 1 OF 1 |

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